

(11)Publication number : 2000-124206
(43)Date of publication of application : 28.04.2000

(51)Int.Cl.

H01L 21/31
H01L 21/027
H01L 21/316
H01L 21/768

(21)Application number : 10-293372
(22)Date of filing : 15.10.1998

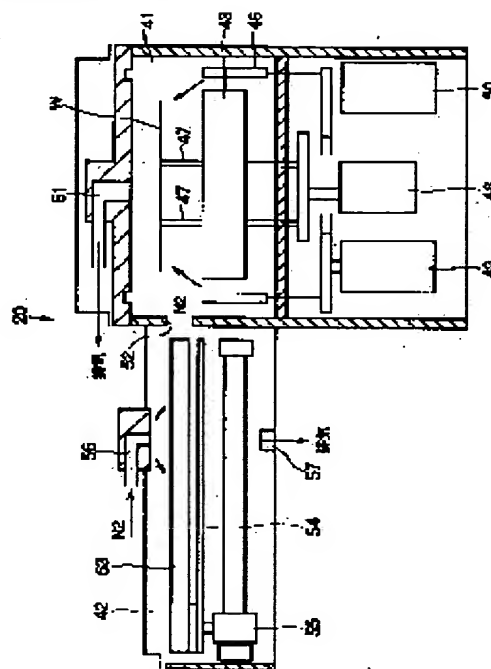
(71)Applicant : TOKYO ELECTRON LTD
(72)Inventor : NAGASHIMA SHINJI
MIYAMOTO HIROYUKI
OGAWA SHIZUO
KOGA SHINJI

(54) COATING FILM FORMING APPARATUS AND HARDENING APPARATUS

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a coating film forming apparatus and a curing apparatus which can manage substrates on which coating films are formed for each substrate at curing the coating films and, in addition, can prevent oxidation of the coating films.

SOLUTION: A DCC treatment unit 20 has a heat treating chamber 41, in which a wafer W is heated and a cooling chamber 42 which communicates with the heat treating chamber 41 and in which the heated wafer W is cooled. The wafer W is heat treated and cooled in an atmosphere containing oxygen at low concentration by evacuating the communicated chambers 41 and 42, while inert gas is supplied to the chambers 41 and 42.



LEGAL STATUS

[Date of request for examination] 08.09.2000

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 3333748

[Date of registration] 26.07.2002

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office